

**IN THE SPECIFICATION**

Please amend the abstract at page 23, lines 2-5, as follows:

A contact [[(15)]] and a copper interconnect line [[(16)]] as an uppermost interconnect layer are buried in an interlayer insulating film [[(14)]]. A pad area [[(17)]] including aluminum alloy (such as AlCu or AlSiCu) is buried in a predetermined area of the copper interconnect line [[(16)]]. A gold wire [[(18)]] is bonded to the pad area [[(17)]].